

CC430F6147 Device Erratasheet

The revision of the device can be identified by the revision letter on the [Package Markings](#) or by the [HW_ID](#) located inside the TLV structure of the device

1 Functional Errata Revision History

Errata impacting device's operation, function or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
ADC39	✓
ADC42	✓
AES1	✓
COMP10	✓
CPU36	✓
CPU46	✓
DMA4	✓
DMA7	✓
DMA10	✓
LCDB5	✓
LCDB6	✓
PMM11	✓
PMM12	✓
PMM14	✓
PMM15	✓
PMM18	✓
PMM20	✓
PMM26	✓
PORT15	✓
PORT19	✓
RF1A1	✓
RF1A2	✓
RF1A3	✓
RF1A5	✓
RF1A6	✓
RF1A8	✓
SYS12	✓
SYS16	✓
UCS11	✓
USCI26	✓
USCI30	✓
USCI35	✓

Errata Number	Rev C
USCI39	✓
USCI40	✓

2 Preprogrammed Software Errata Revision History

Errata impacting pre-programmed software into the silicon by Texas Instruments.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
BSL7	✓
BSL14	✓

3 Debug only Errata Revision History

Errata only impacting debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
EEM17	✓
EEM19	✓
EEM23	✓
JTAG26	✓
JTAG27	✓

4 Fixed by Compiler Errata Revision History

Errata completely resolved by compiler workaround. Refer to specific erratum for IDE and compiler versions with workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
CPU21	✓
CPU22	✓
CPU40	✓

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the `--silicon_errata` option
- [MSP430 Assembly Language Tools](#)

MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check `-msilicon-errata=` and `-msilicon-errata-warn=` options
- [MSP430 GCC User's Guide](#)

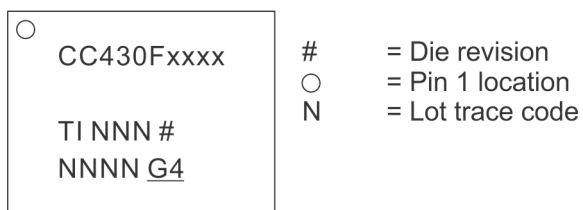
IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

5 Package Markings

RGC64

QFN (RGC), 64 pin



6 Memory-Mapped Hardware Revision (TLV Structure)

Die Revision	TLV Hardware Revision
Rev C	10h

Further guidance on how to locate the TLV structure and read out the HW_ID can be found in the device User's Guide.

7 Detailed Bug Description

ADC39	<i>ADC10_A Module</i>
Category	Functional
Function	Erroneous ADC10 results in extended sample mode
Description	If the extended sample mode is selected (ADC10SHP = 0) and the ADC10CLK is asynchronous to the SHI signal, the ADC10 may generate erroneous results.
Workaround	1) Use the pulse sample mode (ADC10SHP=1) OR 2) Use a synchronous clock for ADC10 and the SHI signal.
ADC42	<i>ADC10_A Module</i>
Category	Functional
Function	ADC stops converting when successive ADC is triggered before the previous conversion ends
Description	Subsequent ADC conversions are halted if a new ADC conversion is triggered while ADC is busy. ADC conversions are triggered manually or by a timer. The affected ADC modes are: <ul style="list-style-type: none"> - sequence-of-channels - repeat-single-channel - repeat-sequence-of-channels (ADC12CTL1.ADC12CONSEQx) In addition, the timer overflow flag cannot be used to detect an overflow (ADC12IFGR2.ADC12TOVIFG).
Workaround	1. For manual trigger mode (ADC12CTL0.ADC12SC), ensure each ADC conversion is completed by first checking ADC12CTL1.ADC12BUSY bit before starting a new conversion. 2. For timer trigger mode (ADC12CTL1.ADC12SHP), ensure the timer period is greater than the ADC sample and conversion time. To recover the conversion halt: <ol style="list-style-type: none"> 1. Disable ADC module (ADC12CTL0.ADC12ENC = 0 and ADC12CTL0.ADC12ON = 0) 2. Re-enable ADC module (ADC12CTL0.ADC12ON = 1 and ADC12CTL0.ADC12ENC = 1) 3. Re-enable conversion
AES1	<i>AES Module</i>
Category	Functional
Function	Ongoing AES operation cannot be aborted by writing to AESAXIN
Description	Writing to AESAXIN register when AESASTAT.AESBUSY bit is set does abort the ongoing AES operation or set the AESACTL0.AESERRFG bit.
Workaround	Always let AES operation run to completion (i.e. do not abort). Ignore the encryption/decryption output if AESAXIN is written when AESASTAT.AESBUSY is set.

BSL7
BSL Module

Category

Software in ROM

Function

BSL does not start after waking up from LPMx.5

Description

When waking up from LPMx.5 mode, the BSL does not start as it does not clear the Lock I/O bit (LOCKLPM5 bit in PM5CTL0 register) on start-up.

Workaround

1. Upgrade the device BSL to the latest version (see Creating a Custom Flash-Based Bootstrap Loader (BSL) Application Note - SLAA450 for more details)

OR

2. Do not use LOCKLPM5 bit (LPMx.5) if the BSL is used but cannot be upgraded.

BSL14
BSL Module

Category

Software in ROM

Function

BSL request to unlock the JTAG

Description

The feature in the BSL to keep the JTAG unlocked by setting the bit BSL_REQ_JTAG_OPEN in the return value has been disabled in this device.

Workaround

None

COMP10
COMP_B Module

Category

Functional

Function

Comparator port output toggles when entering or leaving LPM3/LPM4

Description

The comparator port pin output (CECTL1.CEOUT) erroneously toggles when device enters or leaves LPM3/LPM4 modes under the following conditions:

1) Comparator is disabled (CECTL1.CEON = 0)

AND

2) Output polarity is enabled (CECTL1.CEOUTPOL = 1)

AND

3) The port pin is configured to have CEOUT functionality.

For example, if the CEOUT pin is high when the device is in Active Mode, CEOUT pin becomes low when the device enters LPM3/LPM4 modes.

Workaround

When the comparator is disabled, ensure at least one of the following:

1) Output inversion is disabled (CECTL.CEOUTPOL = 0)

OR

2) Change pin configuration from CEOUT to GPIO with output low.

CPU21
CPUXv2 Module

Category

Compiler-Fixed

Function

Using POPM instruction on Status register may result in device hang up

Description When an active interrupt service request is pending and the POPM instruction is used to set the Status Register (SR) and initiate entry into a low power mode , the device may hang up.

Workaround None. It is recommended not to use POPM instruction on the Status Register.
Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below. --silicon_errata=CPU21
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU22 *CPUXv2 Module*

Category Compiler-Fixed

Function Indirect addressing mode with the Program Counter as the source register may produce unexpected results

Description When using the indirect addressing mode in an instruction with the Program Counter (PC) as the source operand, the instruction that follows immediately does not get executed.

For example in the code below, the ADD instruction does not get executed.

```
mov @PC, R7
add #1h, R4
```

Workaround Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	User is required to add the compiler or assembler flag option below. --silicon_errata=CPU22
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

CPU36 *CPUXv2 Module*

Category Functional

Function PC corruption when single-stepping through flash erase

Description When single-stepping over code that initiates an INFOD Flash memory erase, the program counter is corrupted.

Workaround None.
NOTE: This erratum applies to debug mode only.

CPU40 *CPUXv2 Module*

Category	Compiler-Fixed
Function	PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section
Description	<p>If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.</p> <p>For example, a conditional jump instruction followed by data section (0140h).</p> <pre>@0x8012 Loop DEC.W R6 @0x8014 DEC.W R7 @0x8016 JNZ Loop @0x8018 Value1 DW 0140h</pre>
Workaround	<p>In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.</p> <p>Refer to the table below for compiler-specific fix implementation information.</p>

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v5.51 or later	For the command line version add the following information Compiler: --hw_workaround=CPU40 Assembler:-v1
TI MSP430 Compiler Tools (Code Composer Studio)	v4.0.x or later	
MSP430 GNU Compiler (MSP430-GCC)	Not affected	

CPU46

CPUXv2 Module

Category	Functional
Function	POPM performs unexpected memory access and can cause VMAIFG to be set
Description	<p>When the POPM assembly instruction is executed, the last Stack Pointer increment is followed by an unintended read access to the memory. If this read access is performed on vacant memory, the VMAIFG will be set and can trigger the corresponding interrupt (SFRIE1.VMAIE) if it is enabled. This issue occurs if the POPM assembly instruction is performed up to the top of the STACK.</p>
Workaround	<p>If the user is utilizing C, they will not be impacted by this issue. All TI/IAR/GCC pre-built libraries are not impacted by this bug. To ensure that POPM is never executed up to the memory border of the STACK when using assembly it is recommended to either</p> <ol style="list-style-type: none"> 1. Initialize the SP to <ol style="list-style-type: none"> a. TOP of STACK - 4 bytes if POPM.A is used b. TOP of STACK - 2 bytes if POPM.W is used <p>OR</p> <ol style="list-style-type: none"> 2. Use the POPM instruction for all but the last restore operation. For the the last restore

operation use the POP assembly instruction instead.

For instance, instead of using:

```
POPM.W #5,R13
```

Use:

```
POPM.W #4,R12
POP.W R13
```

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.
TI MSP430 Compiler Tools (Code Composer Studio)	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.
MSP430 GNU Compiler (MSP430-GCC)	Not affected	C code is not impacted by this bug. User using POPM instruction in assembler is required to implement the above workaround manually.

DMA4

DMA Module

Category

Functional

Function

Corrupted write access to 20-bit DMA registers

Description

When a 20-bit wide write to a DMA address register (DMAxSA or DMAxDA) is interrupted by a DMA transfer, the register contents may be unpredictable.

Workaround

1. Design the application to guarantee that no DMA access interrupts 20-bit wide accesses to the DMA address registers.

OR

2. When accessing the DMA address registers, enable the Read Modify Write disable bit (DMARMWDIS = 1) or temporarily disable all active DMA channels (DMAEN = 0).

OR

3. Use word access for accessing the DMA address registers. Note that this limits the values that can be written to the address registers to 16-bit values (lower 64K of Flash).

DMA7

DMA Module

Category

Functional

Function

DMA request may cause the loss of interrupts

Description

If a DMA request starts executing during the time when a module register containing an interrupt flags is accessed with a read-modify-write instruction, a newly arriving interrupt from the same module can get lost. An interrupt flag set prior to DMA execution would not be affected and remain set.

Workaround 1. Use a read of Interrupt Vector registers to clear interrupt flags and do not use read-modify-write instruction.

OR

2. Disable all DMA channels during read-modify-write instruction of specific module registers containing interrupts flags while these interrupts are activated.

DMA10 *DMA Module*

Category Functional

Function DMA access may cause invalid module operation

Description The peripheral modules MPY, CRC, USB, RF1A and FRAM controller in manual mode can stall the CPU by issuing wait states while in operation. If a DMA access to the module occurs while that module is issuing a wait state, the module may exhibit undefined behavior.

Workaround Ensure that DMA accesses to the affected modules occur only when the modules are not in operation. For example with the MPY module, ensure that the MPY operation is completed before triggering a DMA access to the MPY module.

EEM17 *EEM Module*

Category Debug

Function Wrong Breakpoint halt after executing Flash Erase/Write instructions

Description Hardware breakpoints or Conditional Address triggered breakpoints on instructions that follow Flash Erase/Write instructions, stops the debugger at the actual Flash Erase/Write instruction even though the flash erase/write operation has already been executed. The hardware/conditional address triggered breakpoints that are placed on either the next two single opcode instructions OR the next double opcode instruction that follows the Flash Erase/Write instruction are affected by this erratum.

Workaround None. Use other conditional/advanced triggered breakpoints to halt the debugger right after Flash erase/write instructions.

NOTE: This erratum affects debug mode only.

EEM19 *EEM Module*

Category Debug

Function DMA may corrupt data in debug mode

Description When the DMA is enabled and the device is in debug mode, the data written by the DMA may be corrupted when a breakpoint is hit or when the debug session is halted.

Workaround This erratum has been addressed in MSPDebugStack version 3.5.0.1. It is also available in released IDE EW430 IAR version 6.30.3 and CCS version 6.1.1 or newer.

If using an earlier version of either IDE or MSPDebugStack, do not halt or use breakpoints during a DMA transfer.

NOTE: This erratum applies to debug mode only.

EEM23
EEM Module
Category

Debug

Function

EEM triggers incorrectly when modules using wait states are enabled

Description

When modules using wait states (USB, MPY, CRC and FRAM controller in manual mode) are enabled, the EEM may trigger incorrectly. This can lead to an incorrect profile counter value or cause issues with the EEMs data watch point, state storage, and breakpoint functionality.

Workaround

None.

NOTE: This erratum affects debug mode only.

JTAG26
JTAG Module
Category

Debug

Function

LPMx.5 Debug Support Limitations

Description

The JTAG connection to the device might fail at device-dependent low or high supply voltage levels if the LPMx.5 debug support feature is enabled. To avoid a potentially unreliable debug session or general issues with JTAG device connectivity and the resulting bad customer experience Texas Instruments has chosen to remove the LPMx.5 debug support feature from common MSP430 IDEs including TIs Code Composer Studio 6.1.0 with msp430.emu updated to version 6.1.0.7 and IARs Embedded Workbench 6.30.2, which are based on the MSP430 debug stack MSP430.DLL 3.5.0.1 <http://www.ti.com/tool/MSPDS>

TI plans to re-introduce this feature in limited capacity in a future release of the debug stack by providing an IDE override option for customers to selectively re-activate LPMx.5 debug support if needed. Note that the limitations and supply voltage dependencies outlined in this erratum will continue to apply.

For additional information on how the LPMx.5 debug support is handled within the MSP430 IDEs including possible workarounds on how to debug applications using LPMx.5 without toolchain support refer to [Code Composer Studio User's Guide for MSP430 chapter F.4](#) and [IAR Embedded Workbench User's Guide for MSP430 chapter 2.2.5](#).

Workaround

1. If LPMx.5 debug support is deemed functional and required in a given scenario:

a) Do not update the IDE to continue using a previous version of the debug stack such as MSP430.DLL v3.4.3.4.

OR

b) Roll back the debug stack by either performing a clean re-installation of a previous version of the IDE or by manually replacing the debug stack with a prior version such as MSP430.DLL v3.4.3.4 that can be obtained from <http://www.ti.com/tool/MSPDS>.

2. In case JTAG connectivity fails during the LPMx.5 debug mode, the device supply voltage level needs to be raised or lowered until the connection is working.

Do not enable the LPMx.5 debug support feature during production programming.

JTAG27	<i>JTAG Module</i>
Category	Debug
Function	Unintentional code execution after programming via JTAG/SBW
Description	The device can unintentionally start executing code from uninitialized RAM addresses 0x0006 or 0x0008 after being programming via the JTAG or SBW interface. This can result in unpredictable behavior depending on the contents of the address location.
Workaround	<ol style="list-style-type: none"> 1. If using programming tools purchased from TI (MSP-FET, LaunchPad), update to CCS version 6.1.3 later or IAR version 6.30 or later to resolve the issue. 2. If using the MSP-GANG Production Programmer, use v1.2.3.0 or later. 3. For custom programming solutions refer to the specification on MSP430 Programming Via the JTAG Interface User's Guide (SLAU320) revision V or newer and use MSPDebugStack v3.7.0.12 or later. <p>For MSPDebugStack (MSP430.DLL) in CCS or IAR, download the latest version of the development environment or the latest version of the MSPDebugStack</p> <p>NOTE: This only affects debug mode.</p>
LCDB5	<i>LCD_B Module</i>
Category	Functional
Function	Static DC charge can built up on dedicated COMx pins.
Description	If the device is set into LPMx.5, its dedicated COMx pins (not shared with GPIO function) are floating. External leakage paths to these pins can result in dedicated COMx pins being charged. This can lead to static DC voltages being applied to the external LCD display. This might cause long term over-stress to the LCD display and/or cause certain LCD segments to flare up when device wakes up from LPMx.5 mode.
Workaround	Connect a high-resistance resistor between the dedicated COM pins and Vss to permanently discharge the affected pins.
LCDB6	<i>LCD_B Module</i>
Category	Functional
Function	LCD outputs may be corrupted by modifying register fields VLCDx and/or LCDCPEN of LCDCVCTL register while LCDON (LCDCCTL0) is set
Description	Writing to VLCDx and/or LCDCPEN register bits in LCDCVCTL register while LCDON is enabled (LCDON = '1' in LCDCCTL0 register) may corrupt the LCD output due to incorrect start-up of LCD-controller and internal voltage generation.
Workaround	Do not modify VLCDx and/or LCDCPEN bits in LCDCVCTL register while LCDON = '1'
PMM11	<i>PMM Module</i>
Category	Functional
Function	MCLK comes up fast on exit from LPM3 and LPM4
Description	The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4

for up to 6 us. This behavior is masked from affecting code execution by default: SVSL and SVMML run in normal-performance mode and mask CPU execution for 150 us on wakeup from LPM3 and LPM4. However, when the low-side SVS and the SVM are disabled or are operating in full-performance mode (SVMLE = 0 and SVSLE = 0, or SVMLE = 1 and SVSLE = 1) AND MCLK is sourced from the internal DCO running over 4 MHz, 7 MHz, 11 MHz, or 14 MHz at core voltage levels 0, 1, 2, and 3, respectively, the mask lasts only 2 us. MCLK is, therefore, susceptible to run out of spec for 4 us.

Workaround

Set the MCLK divide bits in the Unified Clock System Control 5 Register (UCSCTL5) to divide MCLK by two prior to entering LPM3 or LPM4 (set DIVMx = 001). This prevents MCLK from running out of spec when the CPU wakes from the low-power mode. Following the wakeup from the low-power mode, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, and 3, respectively, before resetting DIVMx to zero and running MCLK at full speed [for example, `__delay_cycles(100)`].

PMM12
PMM Module

Category

Functional

Function

SMCLK comes up fast on exit from LPM3 and LPM4

Description

The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 us. When SMCLK is sourced by the DCO, it is not masked on exit from LPM3 or LPM4. Therefore, SMCLK exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 us. The increased frequency has the potential to change the expected timing behavior of peripherals that select SMCLK as the clock source.

Workaround

- Use XT2 as the SMCLK oscillator source instead of the DCO.

or

- Do not disable the clock request bit for SMCLKREQEN in the Unified Clock System Control 8 Register (UCSCTL8). This means that all modules that depend on SMCLK to operate successfully should be halted or disabled before entering LPM3 or LPM4. If the increased frequency prevents the proper function of an affected module, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before re-enabling the module [for example, `__delay_cycles(100)`].

PMM14
PMM Module

Category

Functional

Function

Increasing the core level when SVS/SVM low side is configured in full-performance mode causes device reset

Description

When the SVS/SVM low side is configured in full performance mode (SVSMLCTL.SVSLFP = 1), the setting time delay for the SVS comparators is ~2us. When increasing the core level in full-performance mode; the core voltage does not settle to the new level before the settling time delay of the SVS/SVM comparator expires. This results in a device reset.

Workaround

When increasing the core level; enable the SVS/SVM low side in normal mode (SVSMLCTL.SVSLFP=0). This provides a settling time delay of approximately 150us allowing the core sufficient time to increase to the expected voltage before the delay expires.

PMM15 *PMM Module*
Category Functional

Function Device may not wake up from LPM2, LPM3, or LPM4

Description Device may not wake up from LPM2, LPM3 or LPM4 if an interrupt occurs within 1 us after the entry to the specified LPMx; entry can be caused either by user code or automatically (for example, after a previous ISR is completed). Device can be recovered with an external reset or a power cycle. Additionally, a PUC can also be used to reset the failing condition and bring the device back to normal operation (for example, a PUC caused by the WDT).

This effect is seen when:

- A write to the SVSMHCTL and SVSMLCTL registers is immediately followed by an LPM2, LPM3, LPM4 entry without waiting the requisite settling time ((PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0)).

or

The following two conditions are met:

- The SVSL module is configured for a fast wake-up or when the SVSL/SVML module is turned off. The affected SVSMLCTL register settings are shaded in the following table.

	SVSLE	SVSLMD	SVSLFP	AM, LPM0/1 SVSL state	Manual SVSMLACE = 0	Automatic SVSMLACE = 1	Wakeup Time LPM2/3/4
					LPM2/3/4 SVSL State	LPM2/3/4 SVSL State	
SVSL	0	x	x	OFF	OFF	OFF	t _{WAKE-UP FAST}
	1	0	0	Normal	OFF	OFF	t _{WAKE-UP SLOW}
	1	0	1	Full Performance	OFF	OFF	t _{WAKE-UP FAST}
	1	1	0	Normal	Normal	OFF	t _{WAKE-UP SLOW}
	1	1	1	Full Performance	Full Performance	Normal	t _{WAKE-UP FAST}
SVML	SVMLE	SVMLFP		AM, LPM0/1 SVML state	Manual SVSMLACE = 0	Automatic SVSMLACE = 1	Wakeup Time LPM2/3/4
					LPM2/3/4 SVML State	LPM2/3/4 SVML State	
	0	x	OFF	OFF	OFF	t _{WAKE-UP FAST}	
	1	0	Normal	Normal	OFF	t _{WAKE-UP SLOW}	
1	1	Full Performance	Full Performance	Normal	t _{WAKE-UP FAST}		

and

-The SVSH/SVMH module is configured to transition from Normal mode to an OFF state when moving from Active/LPM0/LPM1 into LPM2/LPM3/LPM4 modes. The affected SVSMHCTL register settings are shaded in the following table.

	SVSHE	SVSHMD	SVSHFP	AM, LPM0/1 SVSH state	Manual SVSMHACE = 0	Automatic SVSMHACE = 1
					LPM2/3/4 SVSH State	LPM2/3/4 SVSH State
SVSH	0	x	x	OFF	OFF	OFF
	1	0	0	Normal	OFF	OFF
	1	0	1	Full Performance	OFF	OFF
	1	1	0	Normal	Normal	OFF
	1	1	1	Full Performance	Full Performance	Normal
SVMH	SVMHE	SVMHFP		AM, LPM0/1 SVMH state	Manual SVSMHACE = 0	Automatic SVSMHACE = 1
					LPM2/3/4 SVMH State	LPM2/3/4 SVMH State
	0	x		OFF	OFF	OFF
	1	0		Normal	Normal	OFF
1	1		Full Performance	Full Performance	Normal	

Workaround

Any write to the SVSMxCTL register must be followed by a settling delay (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0) before entering LPM2, LPM3, LPM4.

and

1. Ensure the SVSx, SVMx are configured to prevent the issue from occurring by the following:

- Configure the SVSL module for slow wake up (SVSLFP = 0). Note that this will increase the wakeup time from LPM2/3/4 to twakeupslow (~150 us).

or

- Do not configure the SVSH/SVMH such that the modules transition from Normal mode to an OFF state on LPM entry and ensure SVSH/SVMH is in manual mode. Instead force the modules to remain ON even in LPMx. Note that this will cause increased power consumption when in LPMx.

Refer to the MSP430 Driver Library([MSPDRIVERLIB](#)) for proper PMM configuration functions.

Use the following function, PMM15Check (void), to determine whether or not the existing PMM configuration is affected by the erratum. The return value of the function is 1 if the configuration is affected, and 0 if the configuration is not affected.

unsigned char PMM15Check (void)

```
{
// First check if SVSL/SVML is configured for fast wake-up
if ( (!(SVSMLCTL & SVSLE)) || ((SVSMLCTL & SVSLE) && (SVSMLCTL & SVSLFP)) ||
    (!(SVSMLCTL & SVMLE)) || ((SVSMLCTL & SVMLE) && (SVSMLCTL & SVMLFP)) )
{ // Next Check SVSH/SVMH settings to see if settings are affected by PMM15
if ((SVSMHCTL & SVSHE) && !(SVSMHCTL & SVSHFP))
{
if ( (!(SVSMHCTL & SVSHMD)) || ((SVSMHCTL & SVSHMD) &&
(SVSMHCTL & SVSMHACE)) )
```

```

return 1; // SVSH affected configurations
}
if ((SVSMHCTL & SVMHE) && (!(SVSMHCTL & SVMHFP)) && (SVSMHCTL &
SVSMHACE))
return 1; // SVMH affected configurations
}
return 0; // SVS/M settings not affected by PMM15
}
}

```

2. If fast servicing of interrupts is required, add a 150us delay either in the interrupt service routine or before entry into LPM3/LPM4.

PMM18
PMM Module

Category

Functional

Function

PMM supply overvoltage protection falsely triggers POR

Description

The PMM Supply Voltage Monitor (SVM) high side can be configured as overvoltage protection (OVP) using the SVMHOVPE bit of SVSMHCTL register. In this mode a POR should typically be triggered when DVCC reaches ~3.75V.

If the OVP feature of SVM high side is enabled going into LPM234, the SVM might trigger at DVCC voltages below 3.6V (~3.5V) within a few ns after wake-up. This can falsely cause an OVP-triggered POR. The OVP level is temperature sensitive during fail scenario and decreases with higher temperature (85 degC ~3.2V).

Workaround

Use automatic control mode for high-side SVS & SVM (SVSMHCTL.SVSMHACE=1). The SVM high side is inactive in LPM2, LPM3, and LPM4.

PMM20
PMM Module

Category

Functional

Function

Unexpected SVSL/SVML event during wakeup from LPM2/3/4 in fast wakeup mode

Description

If PMM low side is configured to operate in fast wakeup mode, during wakeup from LPM2/3/4 the internal V_{CORE} voltage can experience voltage drop below the corresponding SVSL and SVML threshold (recommendation according to User's Guide) leading to an unexpected SVSL/SVML event. Depending on PMM configuration, this event triggers a POR or an interrupt.

NOTE: As soon the SVSL or the SVML is enabled in Normal performance mode the device is in slow wakeup mode and this erratum does not apply.

In addition, this erratum has sporadic characteristic due to an internal asynchronous circuit. The drop of V_{core} does not have an impact on specified device performance.

Workaround

If SVSL or SVML is required for application (to observe external disruptive events at V_{core} pin) the slow wakeup mode has to be used to avoid unexpected SVSL/SVML events. This is achieved if the SVSL or the SVML is configured in "Normal" performance mode (not disabled and not in "Full" Performance Mode).

PMM26	<i>PMM Module</i>
Category	Functional
Function	Device lock-up if RST pin pulled low during write to SVSMHCTL or SVSMLCTL
Description	<p>Device results in lock-up condition under one of the two scenarios below:</p> <p>1) If RST pin is pulled low during write access to SVSMHCTL, with the RST/NMI pin is configured to reset function and is pulled low (reset event) the device will stop code execution and is continuously held in reset state. RST pin is no longer functional. The only way to come out of the lock-up situation is a power cycle.</p> <p>OR</p> <p>2) If RST pin is pulled low during write access to SVSMLCTL and only if the code that checks for SVSMLDLYIFG==1 is implemented without a timeout. The device will be stuck in the polling loop polling since SVSMLDLYIFG will never be cleared.</p>
Workaround	<p>Follow the sequence below to prevent the lock-up for both use cases:</p> <p>1) Disable RST pin reset function and switch to NMI before access SVSMHCTL or SVSMLCTL.</p> <p>then</p> <p>2) Activate NMI interrupt and handle reset events in this time by SW (optional if reset functionality required during access SVSMHCTL or SVSMLCTL)</p> <p>then</p> <p>3) Enable RST pin reset function after access to SVSMHCTL or SVSMLCTL</p> <p>To prevent lock-up caused by use case #2 a timeout for the SVSMLDLYIFG flag check should be implemented to 300us.</p>
PORT15	<i>PORT Module</i>
Category	Functional
Function	In-system debugging causes the PMALOCKED bit to be always set
Description	<p>The port mapping controller registers cannot be modified when single-stepping or halting at break points between a valid password write to the PMAPWD register and the expected lock of the port mapping (PMAP) registers. This causes the PMAPLOCKED bit to remain set and not clear as expected.</p> <p>Note: This erratum only applies to in-system debugging and is not applicable when operating in free-running mode.</p>
Workaround	Do not single step through or place break points in the port mapping configuration section of code.
PORT19	<i>PORT Module</i>
Category	Functional
Function	Port interrupt may be missed on entry to LPMx.5
Description	If a port interrupt occurs within a small timing window (~1MCLK cycle) of the device entry into LPM3.5 or LPM4.5, it is possible that the interrupt is lost. Hence this interrupt will not trigger a wakeup from LPMx.5.

Workaround	None
RF1A1	<i>RF1A Module</i>
Category	Functional
Function	The PLL lock detector output is not 100% reliable
Description	<p>The PLL lock detector output is not 100% reliable and might toggle even if the PLL is in lock. The PLL is in lock if the lock detector output has a positive transition or is constantly logic high. The PLL is not in lock if the lock detector output is constantly logic low. It is not recommended to check for PLL lock by reading PKTSTATUS[0] with GDOx_CFG=0x0A or PKTSTATUS[2] register with GDOx_CFG=0x0A (x = 0 or 2).</p>
Workaround	<p>PLL lock can be checked reliably by these methods:</p> <ul style="list-style-type: none"> - Program register IOCFGx.GDOx_CFG=0x0A and use the lock detector output available on the GDOx pin as an interrupt for the MCU. A positive transition on the GDOx pin means that the PLL is in lock. It is important to disable for interrupt when waking the chip from SLEEP state as the wake-up might cause the GDOx pin to toggle when it is programmed to output the lock detector. <p>or</p> <ul style="list-style-type: none"> - Read register FSCAL1. The PLL is in lock if the register content is different from 0x3F. <p>With both of the above workarounds the CC1101 PLL calibration should be carried out with the correct settings for TEST0.VCO_SEL_CAL_EN and FSCAL2.VCO_CORE_H_EN. These settings are depending on the operating frequency, and is calculated automatically by SmartRF Studio.</p> <p>Note that the TEST0 register content is not retained in SLEEP state, and thus it is necessary to write to this register as described above when returning from the SLEEP state.</p>
RF1A2	<i>RF1A Module</i>
Category	Functional
Function	RXFIFO overflow flag does not work as intended
Description	<p>In addition to having a 64-byte long RX FIFO, the CC430 has a one byte long pre-fetch buffer between the FIFO and the RF1A module. It also has buffers for status registers and CRC bytes. If more than 65 bytes have been received (the FIFO and the pre-fetch buffer are full) without reading the RX FIFO, the radio will enter RXFIFO_OVERFLOW state. There are, however, some cases where the radio will be stuck in RX state instead of entering RXFIFO_OVERFLOW state. Below is a table showing the register settings that will cause this problem. APPEND_STATUS is found in the PKTCTRL1 register, and CRC_EN is found in the PKTCTRL0 register.</p> <p>Setting IOCFGx=0x06 should mean that the GDO signal is deasserted when the RXFIFO overflows. In the cases where the radio is stuck in RX state, the GDOx pin will not be deasserted.</p> <p>When the radio is stuck in this RX state it draws current as if it was in the RX state, but it will not be able to receive any more data. The only way to get out of this state is to issue an SIDLE strobe and then flush the FIFO (SFRX).</p>
Workaround	In applications where the packets are short enough to fit in the RX FIFO and one wants to wait for the whole packet to be received before starting to read the RX FIFO, for variable packet length mode (PKTCTRL0.LENGTH_CONFIG=1) the PKTLEN register

should be set to 61 to make sure the whole packet including status bytes are 64 bytes or less (length byte (61) + 61 payload bytes + 2 status bytes = 64 bytes) or PKTLEN = 62 if fixed packet length mode is used (PKTCTRL0.LENGTH_CONFIG=0). In application where the packets do not fit in the RX FIFO, one must start reading the RX FIFO before it reaches its limit (64 bytes).

RF1A3
RF1A Module

Category

Functional

Function

Extra Byte Transmitted in TX

Description

If a transmission is aborted (exits TX mode) during the transmission of the first half of any byte, there will be a repetition of the first byte in the next transmission. This issue is caused by a state machine controlling the mod_rd_data signal in the modulator. This signal asserts at the start of transmission of each full byte, then deasserts after half the byte has been transmitted. If the transmission is aborted after a byte has started but before half the byte is transmitted this signal remains asserted and the first byte in the next transmission is repeated.

Workaround

As long as the packet handling features of the CC430 are used, this is not a problem since the chip always exits TX mode after the transmission of the last bit in the last byte of the packet. If, however, one disables the packet handling features (MDMCFG2.SYNC_MODE=0) and wants to exit TX mode manually by strobing IDLE, one should make sure that the IDLE strobe is being issued after clocking out 12 dummy bits (8 dummy bits are necessary due to the TX latency, but since this would mean that transmission is aborted within the first half of a byte, 4 extra bits are added).

RF1A5
RF1A Module

Category

Functional

Function

FIFO Radio Core Interrupt may be triggered independent of the RFINx condition being met

Description

The radio core interrupt flags (RFIFGx) may be set and could generate a radio core interrupt although the corresponding radio input (RFINx) signal condition has not been met.

This is true for the FIFO Mapped Control Signals RFIFG3, RFIFG4, RFIFG5, RFIFG6, RFIFG7, RFIFG8, RFIFG9 (negative edge), and RFIFG10 (negative edge).

Workaround

When handling the radio core interrupts RFIFG3 - RFIFG10, proceed with the ISR only after verifying that the RFINx signal respective to the RFIFGx flag is active.

RF1A6
RF1A Module

Category

Functional

Function

LVERR flag set when radio in SLEEP or IDLE and VCORE = 0, 1

Description

The low-voltage error flag (LVERR) is set when the radio is in the SLEEP or IDLE state and VCORE = 0 or 1, which is contrary to the behavior specified in the [CC430 User's Guide](#).

Workaround

None.

RF1A8	<i>RF1A Module</i>
Category	Functional
Function	RF1AIN10 bit does not reset after the first byte of the RX FIFO is read
Description	The intended behavior of RF1AIN10 bit is that it is set after the last byte is received [into RX FIFO] and reset after the first byte is read from the RX FIFO. However, the RF1AIN10 bit does not reset after the first byte of the RX FIFO is read.
Workaround	Use RF1AIN9 for RX handling instead. To verify the RX packet CRC, enable the RF1A option to append the CRC_OK bit to the end of the RX packet. The CRC_OK bit can be checked after reading out the RX FIFO buffer.
SYS12	<i>SYS Module</i>
Category	Functional
Function	Invalid ACCVIFG when DVcc in the range of 2.4 to 2.6V
Description	<p>A Flash Access Violation Interrupt Flag (ACCVIFG) may be triggered by the Voltage Changed During Program Error bit (VPE) when DVcc is in the range of 2.4 to 2.6V. However the VPE does not signify an invalid flash operation has occurred.</p> <p>If the ACCVIE bit is set and a flash operation is executed in the affected voltage range, an unnecessary interrupt is requested. The bootstrap loader also cannot be used to execute write/erase flash operations in this voltage range, because it exits the flash operation and returns an error on an ACCVIFG event.</p>
Workaround	None
SYS16	<i>SYS Module</i>
Category	Functional
Function	Fast Vcc ramp after device power up may cause a reset
Description	At initial power-up, after Vcc crosses the brownout threshold and reaches a constant level, an abrupt ramp of Vcc at a rate $dV/dT > 1V/100\mu s$ can cause a brownout condition to be incorrectly detected even though Vcc does not fall below the brownout threshold. This causes the device to undergo a reset.
Workaround	Use a controlled Vcc ramp to power up the device.
UCS11	<i>UCS Module</i>
Category	Functional
Function	Modifying UCSCTL4 clock control register triggers an additional erroneous clock request
Description	Changing the SELM/SELS/SELA bits in the UCSCTL4 register will correctly configure the respective clock to use the intended clock source but might also erroneously set XT1/XT2 fault flag if the crystals are not present at XT1/XT2 or not configured in the application firmware. If the NMI interrupt for the OFIFG is enabled, an unintentional NMI interrupt will be triggered and needs to be handled.

NOTE: The XT1/XT2 fault flag can be set regardless of which SELM/SELS/SELA bit combinations are being changed.

Workaround

Clear all the fault flags in UCSCTL7 register once after changing any of the SELM/SELS/SELA bits in the UCSCTL4 register.

If OFIFG-NMI is enabled during clock switching, disable OFIFG-NMI interrupt during changing the SELM/SELS/SELA bits in the UCSCTL4 register to prevent unintended NMI.

Alternatively it can be handled accordingly (clear falsely set fault flags) in the Interrupt Service Routine to ensure proper OFIFG clearing.

USCI26
USCI Module
Category

Functional

Function

Tbuf parameter violation in I2C multi-master mode

Description

In multi-master I2C systems the timing parameter Tbuf (bus free time between a stop condition and the following start) is not guaranteed to match the I2C specification of 4.7us in standard mode and 1.3us in fast mode. If the UCTXSTT bit is set during a running I2C transaction, the USCI module waits and issues the start condition on bus release causing the violation to occur.

Note: It is recommended to check if UCBBUSY bit is cleared before setting UCTXSTT=1.

Workaround

None

USCI30
USCI Module
Category

Functional

Function

I2C mode master receiver / slave receiver

Description

When the USCI I2C module is configured as a receiver (master or slave), it performs a double-buffered receive operation. In a transaction of two bytes, once the first byte is moved from the receive shift register to the receive buffer the byte is acknowledged and the state machine allows the reception of the next byte.

If the receive buffer has not been cleared of its contents by reading the UCxBXBUF register while the 7th bit of the following data byte is being received, an error condition may occur on the I2C bus. Depending on the USCI configuration the following may occur:

- 1) If the USCI is configured as an I2C master receiver, an unintentional repeated start condition can be triggered or the master switches into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case.
- 2) If the USCI is configured as I2C slave receiver, the slave can switch to an idle state stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine will notify the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the 7th bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition will not occur.

Workaround

a) The error condition can be avoided altogether by servicing the UCBxRXIFG in a timely manner. This can be done by (a) servicing the interrupt and ensuring UCBxRXBUF is read promptly or (b) Using the DMA to automatically read bytes from receive buffer upon UCBxRXIFG being set.

OR

b) In case the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLOW is set for atleast three USCI bit clock cycles i.e. $3 \times t(\text{BitClock})$.

Note that the last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes follow the workaround:

Code flow for workaround

- (1) Enter RX ISR for reading receiving bytes
- (2) Check if UCSCLOW.UCBxSTAT == 1
- (3) If no, repeat step 2 until set
- (4) If yes, repeat step 2 for a time period $> 3 \times t(\text{BitClock})$ where $t(\text{BitClock}) = 1 / f(\text{BitClock})$
- (5) If window of $3 \times t(\text{BitClock})$ cycles has elapsed, it is safe to read UCBxRXBUF

USCI35
USCI Module

Category

Functional

Function

Violation of setup and hold times for (repeated) start in I2C master mode

Description

In I2C master mode, the setup and hold times for a (repeated) START, $t_{\text{SU,STA}}$ and $t_{\text{HD,STA}}$ respectively, can be violated if SCL clock frequency is greater than 50kHz in standard mode (100kbps). As a result, a slave can receive incorrect data or the I2C bus can be stalled due to clock stretching by the slave.

Workaround

If using repeated start, ensure SCL clock frequencies is $< 50\text{kHz}$ in I2C standard mode (100 kbps).

USCI39
USCI Module

Category

Functional

Function

USCI I2C IFGs UCSTTIFG, UCSTPIFG, UCNACKIFG

Description

Unpredictable code execution can occur if one of the hardware-clear-able IFGs UCSTTIFG, UCSTPIFG or UCNACKIFG is set while the global interrupt enable is set by software (GIE=1). This erratum is triggered if ALL of the following events occur in following order:

1. Pending Interrupt: One of the UCxIFG=1 AND UCxIE=1 while GIE=0
2. The GIE is set by software (e.g. EINT)
3. The pending interrupt is cleared by hardware (external I2C event) in a time window of 1 MCLK clock cycle after the "EINT" instruction is executed.

Workaround

Disable the UCSTTIE, UCSTPIE and UCNACKIE before the GIE is set. After GIE is set, the local interrupt enable flags can be set again.

Assembly example:

```

bic #UCNACKIE+UCSTPIE+UCSTTIE, UCBxIE ; disable all self-clearing interrupts
NOP
EINT
bis #UCNACKIE+UCSTPIE+UCSTTIE, UCBxIE ; enable all self-clearing interrupts

```

USCI40
USCI Module

Category

Functional

Function

SPI Slave Transmit with clock phase select = 1

Description

In SPI slave mode with clock phase select set to 1 (UCAxCTLW0.UCCKPH=1), after the first TX byte, all following bytes are shifted by one bit with shift direction dependent on UCMSB. This is due to the internal shift register getting pre-loaded asynchronously when writing to the USCIA TXBUF register. TX data in the internal buffer is shifted by one bit after the RX data is received.

Workaround

Reinitialize TXBUF before using SPI and after each transmission.

If transmit data needs to be repeated with the next transmission, then write back previously read value:

```
UCAxTXBUF = UCAxTXBUF;
```

8 Document Revision History

Changes from family erratasheet to device specific erratasheet.

1. Package RGC64 was removed

Changes from device specific erratasheet to document Revision A.

1. Errata PORT19 was added to the errata documentation.
2. Errata PMM18 was added to the errata documentation.

Changes from document Revision A to Revision B.

1. Errata DMA10 was added to the errata documentation.
2. Errata BSL7 was added to the errata documentation.
3. Errata LCDB5 was added to the errata documentation.
4. Errata LCDB6 was added to the errata documentation.

Changes from document Revision B to Revision C.

1. DMA10 Description was updated.
2. DMA10 Function was updated.

Changes from document Revision C to Revision D.

1. DMA10 Description was updated.
2. Errata EEM23 was added to the errata documentation.
3. Errata CPU43 was added to the errata documentation.

Changes from document Revision D to Revision E.

1. SYS16 Description was updated.
2. CPU43 Description was updated.
3. Device TLV Hardware Revision information added to erratasheet.

Changes from document Revision E to Revision F.

1. Errata PMM20 was added to the errata documentation.
2. Errata USCI35 was added to the errata documentation.

Changes from document Revision F to Revision G.

1. BSL7 Workaround was updated.
2. BSL7 Function was updated.

Changes from document Revision G to Revision H.

1. EEM19 Workaround was updated.
2. EEM17 Workaround was updated.
3. CPU43 Description was updated.
4. EEM23 Workaround was updated.
5. EEM17 Description was updated.
6. EEM23 Description was updated.
7. Errata ADC39 was added to the errata documentation.
8. EEM19 Description was updated.

Changes from document Revision H to Revision I.

1. DMA10 Workaround was updated.
2. DMA10 Description was updated.
3. DMA10 Function was updated.

Changes from document Revision I to Revision J.

1. CPU40 Workaround was updated.
2. EEM19 Workaround was updated.

3. Errata USCI39 was added to the errata documentation.
4. Package Markings section was updated.
5. EEM23 Workaround was updated.
6. EEM23 Description was updated.
7. Errata ADC42 was added to the errata documentation.
8. EEM23 Function was updated.
9. EEM19 Description was updated.

Changes from document Revision J to Revision K.

1. Errata USCI40 was added to the errata documentation.
2. Errata CPU43 was removed from the errata documentation.
3. PMM18 Workaround was updated.

Changes from document Revision K to Revision L.

1. DMA7 Workaround was updated.
2. EEM23 Description was updated.
3. DMA7 Description was updated.

Changes from document Revision L to Revision M.

1. USCI39 Description was updated.
2. Errata AES1 was added to the errata documentation.

Changes from document Revision M to Revision N.

1. Errata BSL14 was added to the errata documentation.
2. Errata JTAG26 was added to the errata documentation.

Changes from document Revision N to Revision O.

1. EEM19 Workaround was updated.
2. Errata PMM26 was added to the errata documentation.

Changes from document Revision O to Revision P.

1. UCS11 Workaround was updated.
2. UCS11 Description was updated.
3. UCS11 Function was updated.

Changes from document Revision P to Revision Q.

1. Errata JTAG27 was added to the errata documentation.
2. Errata COMP10 was added to the errata documentation.

Changes from document Revision Q to Revision R.

1. USCI39 Workaround was updated.
2. SYS12 Description was updated.
3. Errata CPU46 was added to the errata documentation.

Changes from document Revision R to Revision S.

1. CPU21 was added to the errata documentation.
2. CPU22 was added to the errata documentation.
3. Workaround for CPU40 was updated.
4. Workaround for CPU46 was updated.
5. Workaround for PMM15 was updated.

Changes from document Revision S to Revision T.

1. Workaround for CPU46 was updated.

Changes from document Revision T to Revision U.

1. Workaround for PMM15 was updated.

Changes from document Revision U to Revision V.

1. Erratasheet format update.
2. Added errata category field to "Detailed bug description" section

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